

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3226528

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TAKESHI TOKUYAMA	12/22/2014
KINYA NAKATSU	12/24/2014
AKIRA MIMA	12/24/2014
YUKIO HATTORI	12/24/2014
TOSHIYA SATOH	12/22/2014
RECEIVING PARTY DATA	
Name:	HITACHI AUTOMOTIVE SYSTEMS, LTD.
Street Address:	2520, TAKABA
City:	HITACHINAKA-SHI, IBARAKI
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14421508
CORRESPONDENCE DATA	
Fax Number:	(202)628-8844
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2026242500
Email:	elawson@crowell.com
Correspondent Name:	CROWELL & MORING LLP
Address Line 1:	1001 PENNSYLVANIA AVENUE, N.W.
Address Line 4:	WASHINGTON, D.C. 20004
ATTORNEY DOCKET NUMBER:	106734.67426US
NAME OF SUBMITTER:	MICHAEL H. JACOBS
SIGNATURE:	/Michael H. Jacobs/
DATE SIGNED:	02/13/2015
Total Attachments: 1	
source=67426US_Assignment#page1.tif	

ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi Automotive Systems, Ltd., a corporation organized under the laws of Japan, located at 2520, Takaba, Hitachinaka-shi, Ibaraki Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Automotive Systems, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

POWER SEMICONDUCTOR MODULE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi Automotive Systems, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made,

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Automotive Systems, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Takeshi Tokuyama</u> Takeshi TOKUYAMA	<u>12/22/2014</u>
2) <u>Kinya Nakatsu</u> Kinya NAKATSU	<u>12/24/2014</u>
3) <u>Akira Mima</u> Akira MIMA	<u>12/24/2014</u>
4) <u>Yukio Hattori</u> Yukio HATTORI	<u>12/24/2014</u>
5) <u>Toshiya Satoh</u> Toshiya SATOH	<u>12/22/2014</u>
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____